Programme

Date: Wednesday May 11, 2016
Location: MacDermid Enthone, Birmingham, UK
Language: English

10:30 hrs Welcome and Introduction Paul Waldner
10:45 hrs Introduction Paul Bray, MacDermid Enthone
11:00 hrs Plating Subcontractor for the PCB Industry
John Fischer, Hofstetter PCB AG
11:45 hrs Systek Electroplate Process-Through Hole Filling
Andrew Barlow, MacDermid Enthone
12:15 hrs Lunch
13:15 hrs Factory tour MacDermid Enthone
14:30 hrs New generation blind microvia filling by copper electroplating
Dr. Michael Dietterle, Dr. Ing. Max Schlötter GmbH & Co. KG
15:00 hrs A Novel Approach to Finer Structures and Reliable High Speed Circuit Performance using Full Additive and Semi-Additive Processes
Paul Waldner, Multiline International Europa LP on behalf of e-Surface
15:30 hrs Coffee break
16:00 hrs Advances in electroless and galvanic copper for reliable via connections
Stuart Sullivan, DOW Electronic Materials
16:30 Uhr Copperplating on PCBs
Paul Comer, Graphic Plc
17:00 Uhr Closing remarks, Paul Waldner

Please visit www.eipc.org for the latest news

Sponsored by: